TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20150310002
Qualification of Vanguard Facility as an additional FAB site source for select OPA2364xx devices in the 0.60UM Process
Change Notification / Sample Request

Date: 3/13/2015
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

20150310002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA2364IDGKT	null
OPA2364AID	null
OPA2364AIDGKT	null
OPA2364AIDR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN20150310002	**PCN Date:**	03/13/2015
Title:	Qualification of Vanguard Facility as an additional FAB site source for selected devices in the 0.60UM process		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
***Proposed 1st Ship Date:**	06/13/2015	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its Vanguard fabrication facility as an additional wafer FAB source for the selected devices listed in "Product Affected" section.

Currently Qualified Sites, Process, wafer dia.	**Additional Site, Process, wafer dia.**
TMSC-WF2, 0.60UM, 200mm	**Vanguard, VIS 0.6UM DPDM, 200mm**

The 0.6um DPDM process has been running in production successfully in Vanguard since 2006. Qualification details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
TSMC-WF2	TS2	TWN

New

Chip Site	Chip site code (20L)	Chip country code (21L)
Vanguard (VIS)	**VAN**	**TWN**

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
G4
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

OPA2364AID	OPA2364AIDGKT	OPA2364ID	OPA2364IDGKTG4
OPA2364AIDG4	OPA2364AIDGKTG4	OPA2364IDGKR	OPA2364IDR
OPA2364AIDGKR	OPA2364AIDR	OPA2364IDGKRG4	OPA2364IDRG4
OPA2364AIDGKRG4	OPA2364AIDRG4	OPA2364IDGKT	

Qualification Report

OPA2364 Vanguard (aka VIS FAB - qualified process flow 0.5um/0.6um) model transfer from TSMC FAB2

Approved 01/23/2015

Attributes	Qual Device: OPA2364AIDGK	QBS Process: DDC112Y	QBS Process: OPA343U	QBS Process: TSC2046IPW
Assembly Site	ASE SHANGHAI	CRS	OSE	TAI
Package Family	VSSOP	TQFP	SOIC	TSSOP
Flammability Rating	UL 94 V-0	UL94 Class V-0	UL94 Class V-0	UL94 Class V-0
Wafer Fab Site	VANGUARD-8	VANGUARD	VANGUARD	VANGUARD
Wafer Fab Process	0.6/0.5um DPDM	0.5/0.6um DPDM	0.5/0.6um DPDM	0.5/0.6um DPDM

Test Name / Condition	Duration	Qual Device: OPA2364AIDGK	QBS Process: DDC112Y	QBS Process: OPA343U	QBS Process: TSC2046IPW
Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	-	1/77/0
Autoclave 121C	96 Hours	-	1/77/0	1/77/0	1/77/0
Temperature Cycle, -65/150C	500 Cycles	3/231/0	1/77/0	1/77/0	1/77/0
High Temp. Storage Bake, 150C	1000 Hours	-	1/77/0	-	-
High Temp. Storage Bake, 170C	420 Hours	-	-	-	1/77/0
Thermal Shock -65/150C	500 Cycles	-	1/77/0	-	1/77/0
Life Test, 125C	1000 Hours	-	-	-	-
Life Test, 150C	300 Hours	3/231/0	1/77/0	1/77/0	1/77/0
ESD - HBM	2500 V	2/6/2000	-	-	-
ESD - CDM	1000 V	3/9/2000	1/3/2000	-	1/3/2000
Latch-up	(per JESD78)	3/18/2000	1/6/2000	1/6/2000	1/6/2000
Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com